



STF11N65K3

N-channel 650 V, 0.765 Ω , 11 A, TO-220FP
SuperMESH3™ Power MOSFET

Features

Type	V _{DSS}	R _{DS(on)} max	I _D	P _{tot}
STF11N65K3	650 V	< 0.85 Ω	11 A	35 W

- 100% avalanche tested
- Extremely high dv/dt capability
- Gate charge minimized
- Very low intrinsic capacitances
- Improved diode reverse recovery characteristics
- Zener-protected

Applications

- Switching applications

Description

This device is an N-channel Zener-protected SuperMESH3™ Power MOSFET developed using STMicroelectronics' SuperMESH™ technology, achieved through optimization of ST's well established strip-based PowerMESH™ layout. In addition to a significant reduction in on-resistance, this device is designed to ensure a high level of dv/dt capability for the most demanding applications.

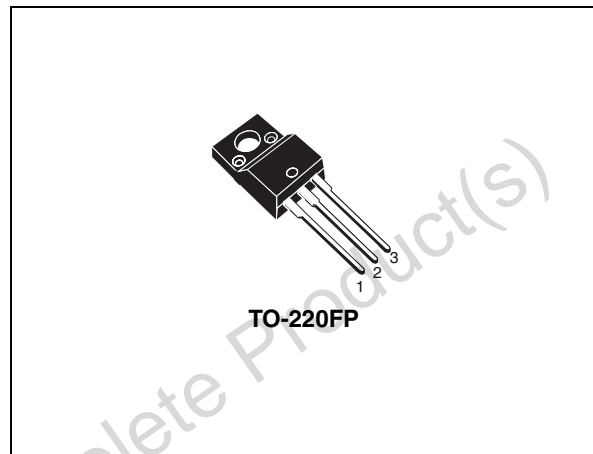


Figure 1. Internal schematic diagram

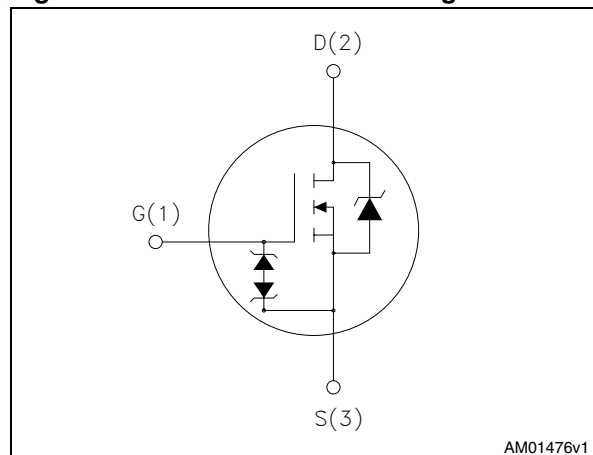


Table 1. Device summary

Order codes	Marking	Package	Packaging
STF11N65K3	11N65K3	TO-220FP	Tube

Contents

1	Electrical ratings	3
2	Electrical characteristics	4
	2.1 Electrical characteristics (curves)	6
3	Test circuits	9
4	Package mechanical data	10
5	Revision history	12

Obsolete Product(s) - Obsolete Product(s)

1 Electrical ratings

Table 2. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{DSS}	Drain source voltage ($V_{GS}=0$)	650	V
V_{GS}	Gate-source voltage	± 30	V
I_D	Drain current (continuous) at $T_C = 25\text{ }^\circ\text{C}$	11	A
I_D	Drain current (continuous) at $T_C = 100\text{ }^\circ\text{C}$	6.3	A
$I_{DM}^{(1)}$	Drain current (pulsed)	40	A
P_{TOT}	Total dissipation at $T_C = 25\text{ }^\circ\text{C}$	35	W
I_{AR}	Max current during repetitive or single pulse avalanche (pulse width limited by T_{JMAX})	7.2	A
E_{AS}	Single pulse avalanche energy ⁽²⁾	212	mJ
	Derating factor	0.28	W/ $^\circ\text{C}$
dv/dt ⁽³⁾	Peak diode recovery voltage slope	12	V/ns
$V_{ESD(G-S)}$	G-S ESD (HBM $C=100\text{ pF}$, $R=1.5\text{ k}\Omega$)	2500	V
V_{ISO}	Insulation withstand voltage (RMS) from all three leads to external heat sink ($t=1\text{ s}$; $T_C=25\text{ }^\circ\text{C}$)	2500	V
T_j T_{stg}	Operating junction temperature Storage temperature	-55 to 150	$^\circ\text{C}$

1. Pulse width limited by safe operating area.
2. Starting $T_j = 25\text{ }^\circ\text{C}$, $I_D = I_{AR}$, $V_{DD} = 50\text{ V}$
3. $I_{SD} \leq 11\text{ A}$, $di/dt \leq 400\text{ A}/\mu\text{s}$, $V_{DD} = 80\% V_{(BR)DSS}$, $V_{DS\text{ peak}} < V_{(BR)DSS}$

Table 3. Thermal data

Symbol	Parameter	Value	Unit
$R_{thj-case}$	Thermal resistance junction-case max	3.57	$^\circ\text{C}/\text{W}$
$R_{thj-amb}$	Thermal resistance junction-ambient max	62.5	$^\circ\text{C}/\text{W}$
T_l	Maximum lead temperature for soldering purpose	300	$^\circ\text{C}$

2 Electrical characteristics

(T_{case} = 25 °C unless otherwise specified).

Table 4. On /off states

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
V _{(BR)DSS}	Drain-source breakdown voltage (V _{GS} = 0)	I _D = 1 mA	650			V
I _{DSS}	Zero gate voltage drain current (V _{GS} = 0)	V _{DS} = 650 V V _{DS} = 650 V, T _C = 125 °C			1 50	μA μA
I _{GSS}	Gate-body leakage current (V _{DS} = 0)	V _{GS} = ± 20 V			10	μA
V _{GS(th)}	Gate threshold voltage	V _{DS} = V _{GS} , I _D = 100 μA	3		4.5	V
R _{DS(on)}	Static drain-source on resistance	V _{GS} = 10 V, I _D = 3.6 A		0.765	0.85	Ω

Table 5. Dynamic

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C _{iss}	Input capacitance	V _{DS} = 50 V, f = 1 MHz, V _{GS} = 0	-	1180	-	pF
C _{oss}	Output capacitance			125		pF
C _{rss}	Reverse transfer capacitance			14		pF
C _{oss eq.}	Equivalent output capacitance	V _{DS} = 0 to 520 V, V _{GS} = 0	-	77	-	pF
R _G	Intrinsic gate resistance	f = 1 MHz open drain	-	3	-	Ω
Q _g	Total gate charge	V _{DD} = 520 V, I _D = 7.2 A, V _{GS} = 10 V (see Figure 16)	-	42	-	nC
Q _{gs}	Gate-source charge			7.4		nC
Q _{gd}	Gate-drain charge			23		nC

Table 6. Switching times

Symbol	Parameter	Test conditions	Min.	Typ.	Max	Unit
t _{d(on)}	Turn-on delay time	V _{DD} = 310 V, I _D = 3.5 A, R _G = 4.7 Ω, V _{GS} = 10 V (see Figure 15)	-	14.5	-	ns
t _r	Rise time			14		ns
t _{d(off)}	Turn-off-delay time			44		ns
t _f	Fall time			35		ns

Table 7. Source drain diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
I_{SD}	Source-drain current		-		7.2	A
$I_{SDM}^{(1)}$	Source-drain current (pulsed)		-		28.8	A
$V_{SD}^{(2)}$	Forward on voltage	$I_{SD} = 7\text{ A}, V_{GS} = 0$	-		1.5	V
t_{rr}	Reverse recovery time	$I_{SD} = 7\text{ A}, di/dt = 100\text{A}/\mu\text{s}$ $V_{DD} = 60\text{ V}$ (see Figure 20)	-	320		ns
Q_{rr}	Reverse recovery charge			2		μC
I_{RRM}	Reverse recovery current			13		A
t_{rr}	Reverse recovery time	$I_{SD} = 7\text{ A}, di/dt = 100\text{ A}/\mu\text{s}$ $V_{DD} = 60\text{ V}, T_j = 150\text{ }^\circ\text{C}$ (see Figure 20)	-	410		ns
Q_{rr}	Reverse recovery charge			2.9		μC
I_{RRM}	Reverse recovery current			14		A

1. Pulse width limited by safe operating area

2. Pulsed: Pulse duration = 300 μs , duty cycle 1.5%

Table 8. Gate-source Zener diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
BV_{GSO}	Gate-source breakdown voltage	$I_{gs} = \pm 1\text{ mA}$ (open drain)	30	-	-	V

The built-in back-to-back Zener diodes have specifically been designed to enhance not only the device's ESD capability, but also to make them safely absorb possible voltage transients that may occasionally be applied from gate to source. In this respect the Zener voltage is appropriate to achieve an efficient and cost-effective intervention to protect the device's integrity. These integrated Zener diodes thus avoid the usage of external components.

2.1 Electrical characteristics (curves)

Figure 2. Safe operating area

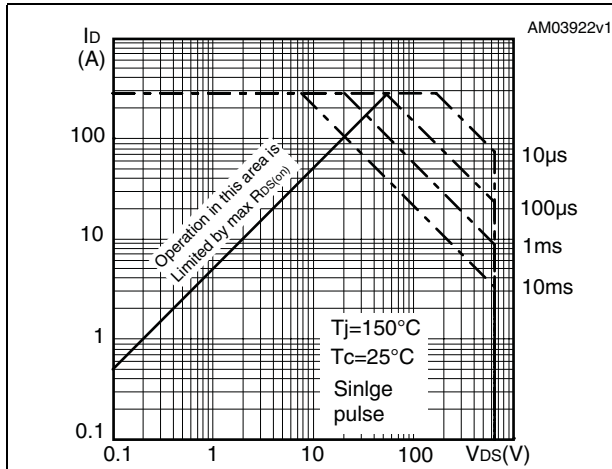


Figure 3. Thermal impedance

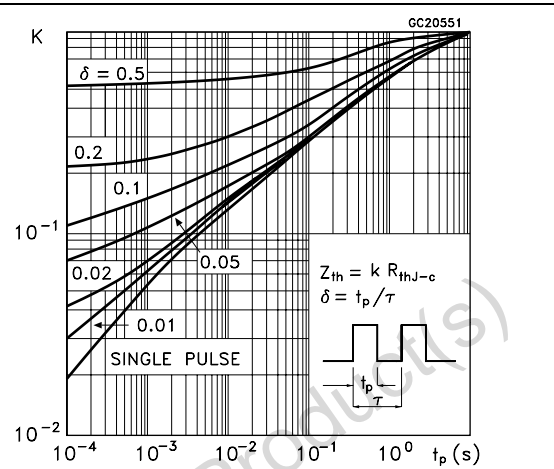


Figure 4. Output characteristics

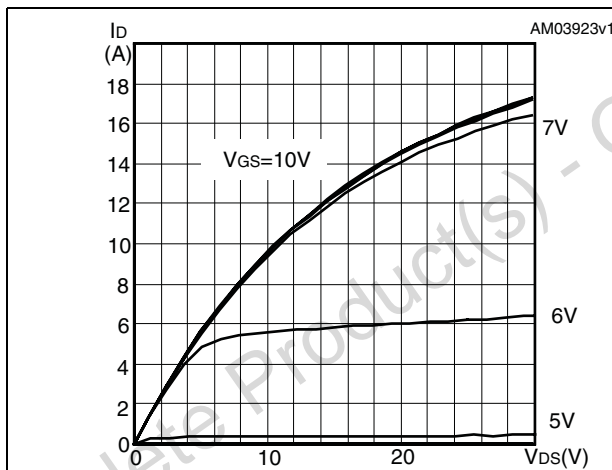


Figure 5. Transfer characteristics

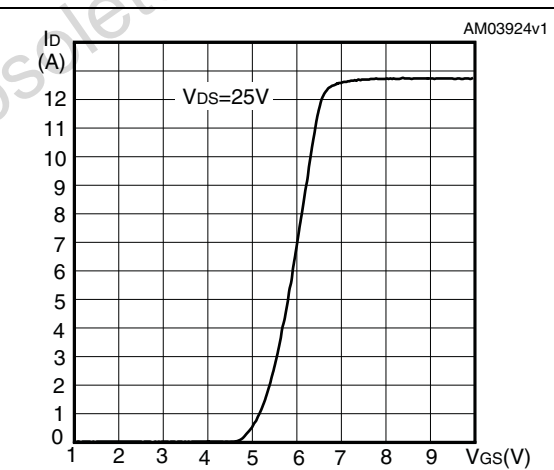


Figure 6. Normalized BV_{DSS} vs temperature

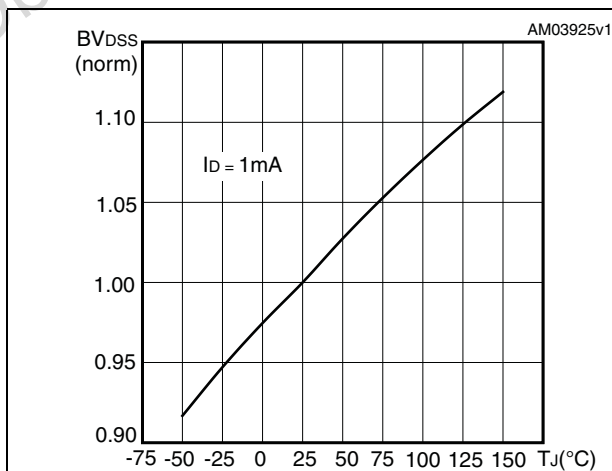


Figure 7. Static drain-source on resistance

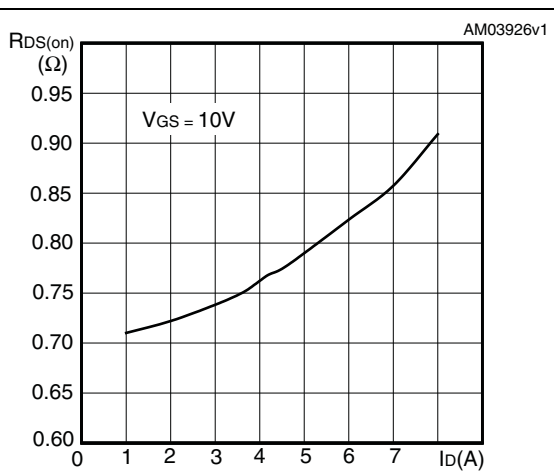


Figure 8. Output capacitance stored energy Figure 9. Capacitance variations

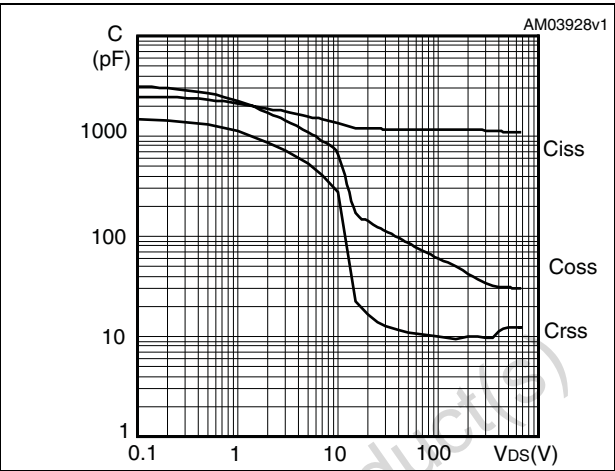
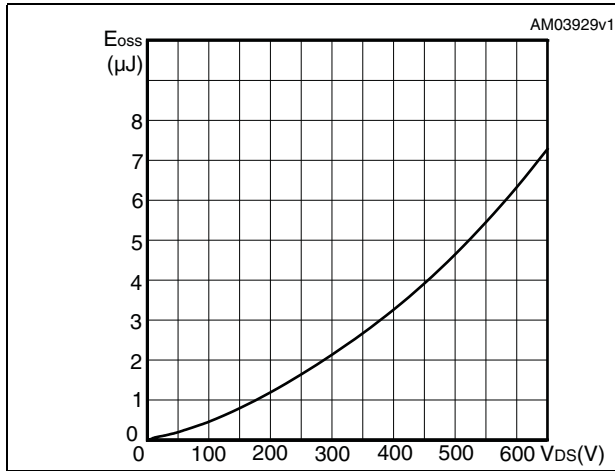


Figure 10. Gate charge vs gate-source voltage

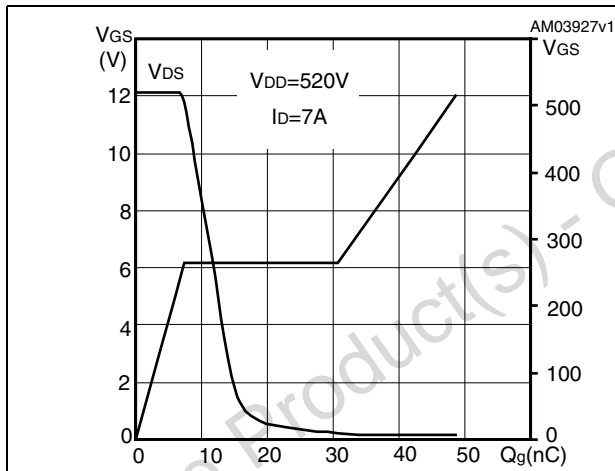


Figure 11. Normalized on resistance vs temperature

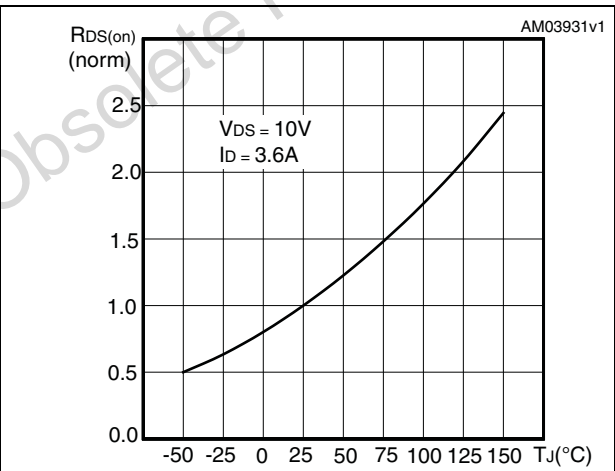


Figure 12. Normalized gate threshold voltage vs temperature

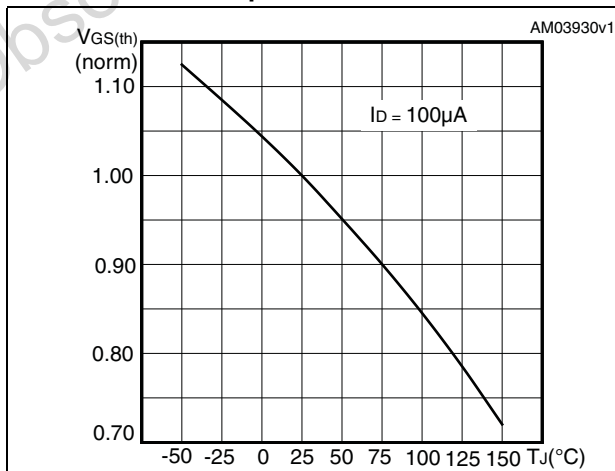


Figure 13. Maximum avalanche energy vs temperature

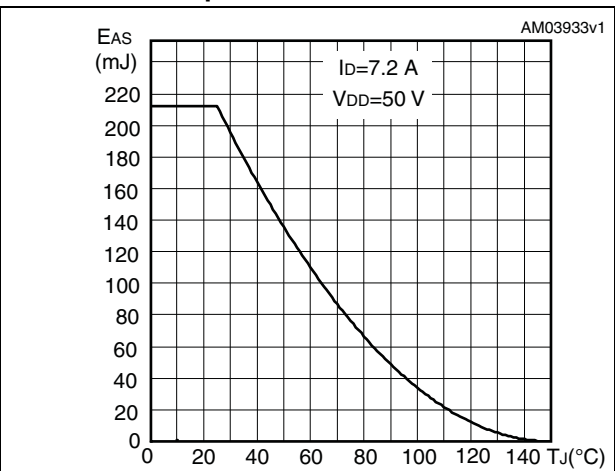
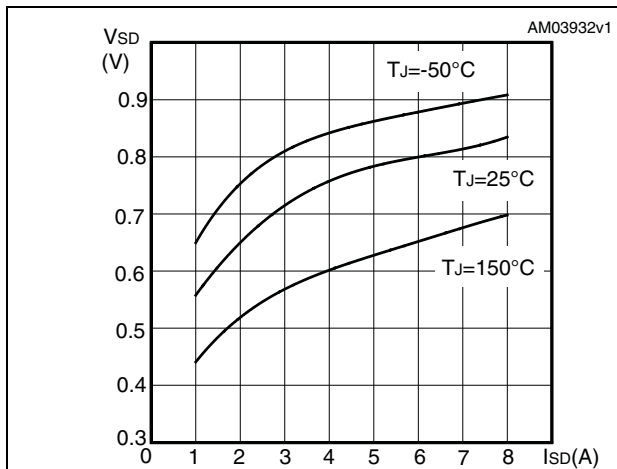


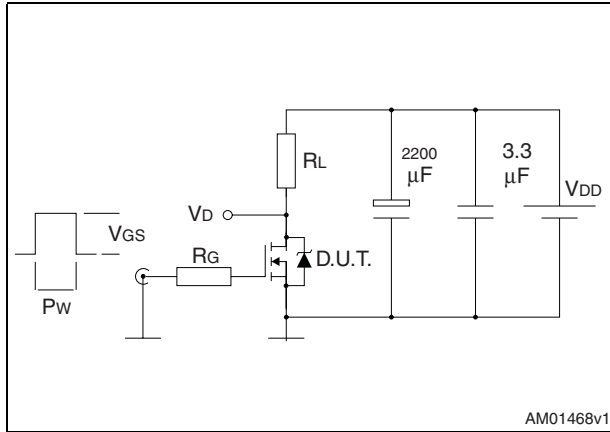
Figure 14. Source-drain diode forward characteristics



Obsolete Product(s) - Obsolete Product(s)

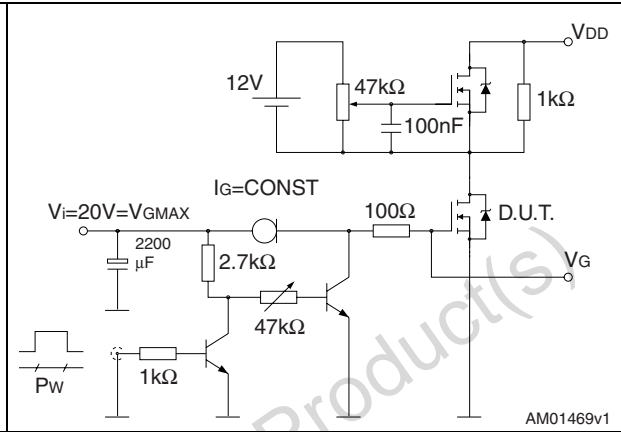
3 Test circuits

Figure 15. Switching times test circuit for resistive load



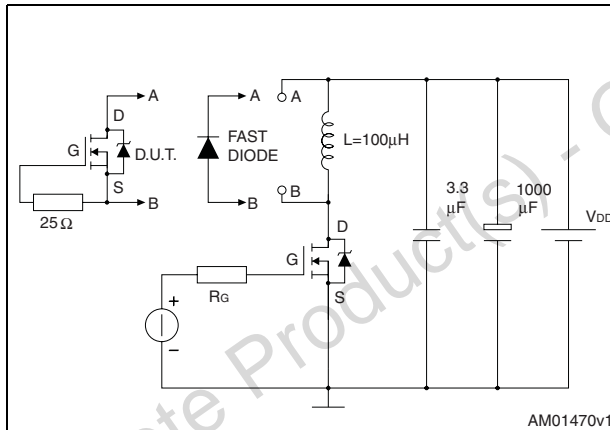
AM01468v1

Figure 16. Gate charge test circuit



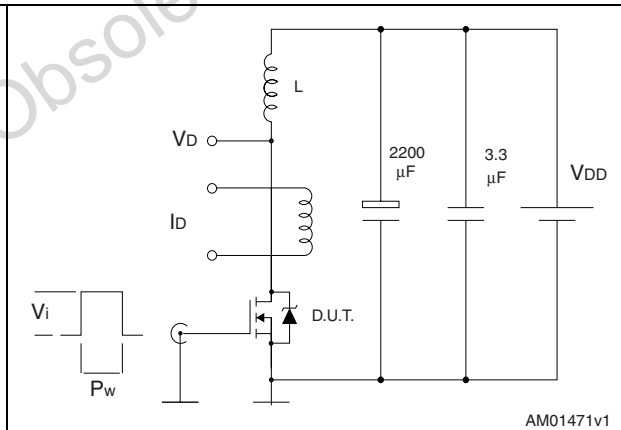
AM01469v1

Figure 17. Test circuit for inductive load switching and diode recovery times



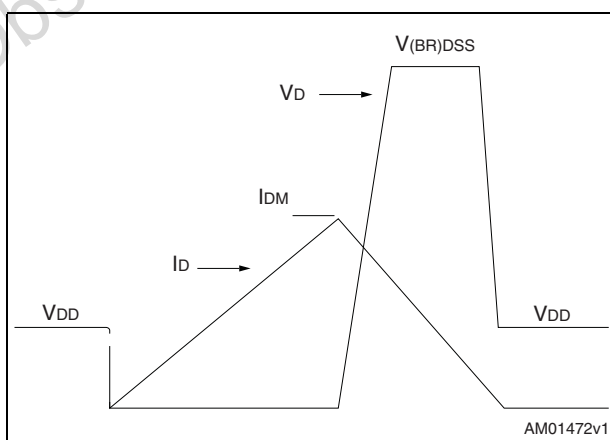
AM01470v1

Figure 18. Unclamped inductive load test circuit



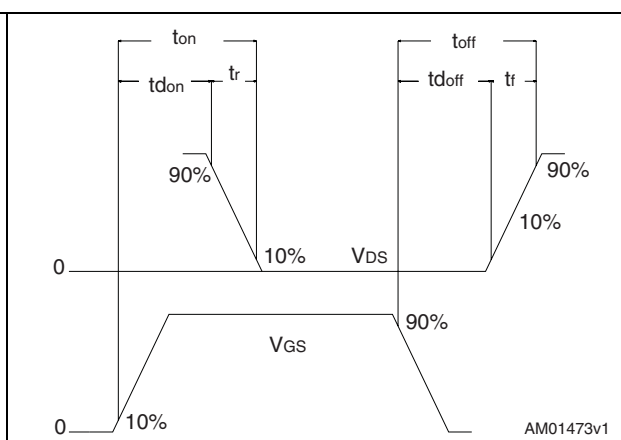
AM01471v1

Figure 19. Unclamped inductive waveform



AM01472v1

Figure 20. Switching time waveform



AM01473v1

4 Package mechanical data

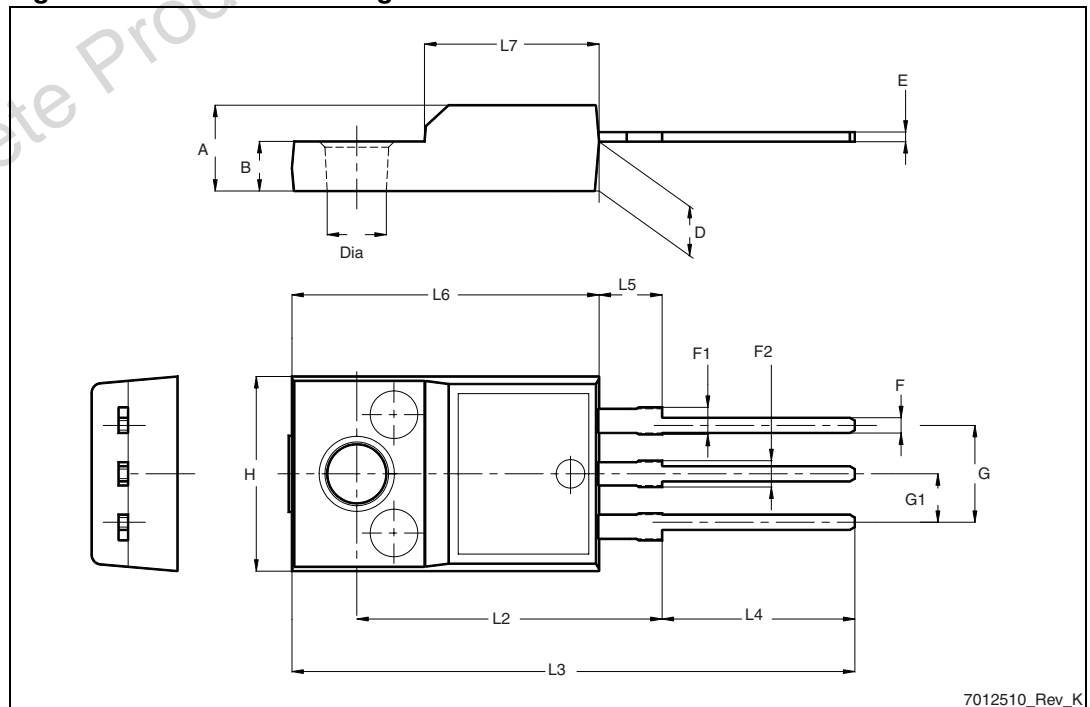
In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK is an ST trademark.

Obsolete Product(s) - Obsolete Product(s)

Table 9. TO-220FP mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.4		4.6
B	2.5		2.7
D	2.5		2.75
E	0.45		0.7
F	0.75		1
F1	1.15		1.70
F2	1.15		1.70
G	4.95		5.2
G1	2.4		2.7
H	10		10.4
L2		16	
L3	28.6		30.6
L4	9.8		10.6
L5	2.9		3.6
L6	15.9		16.4
L7	9		9.3
Dia	3		3.2

Figure 21. TO-220FP drawing



5 Revision history

Table 10. Document revision history

Date	Revision	Changes
10-Sep-2010	1	First release
03-Oct-2011	2	Updated <i>Figure 6: Normalized BV_{DSS} vs temperature</i> , <i>Figure 7: Static drain-source on resistance</i> , <i>Figure 10: Gate charge vs gate-source voltage</i> , <i>Figure 11: Normalized on resistance vs temperature</i> , <i>Figure 12: Normalized gate threshold voltage vs temperature</i> . Minor text changes.

Obsolete Product(s) - Obsolete Product(s)

Please Read Carefully:

Information in this document is provided solely in connection with ST products. STMicroelectronics NV and its subsidiaries ("ST") reserve the right to make changes, corrections, modifications or improvements, to this document, and the products and services described herein at any time, without notice.

All ST products are sold pursuant to ST's terms and conditions of sale.

Purchasers are solely responsible for the choice, selection and use of the ST products and services described herein, and ST assumes no liability whatsoever relating to the choice, selection or use of the ST products and services described herein.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted under this document. If any part of this document refers to any third party products or services it shall not be deemed a license grant by ST for the use of such third party products or services, or any intellectual property contained therein or considered as a warranty covering the use in any manner whatsoever of such third party products or services or any intellectual property contained therein.

UNLESS OTHERWISE SET FORTH IN ST'S TERMS AND CONDITIONS OF SALE ST DISCLAIMS ANY EXPRESS OR IMPLIED WARRANTY WITH RESPECT TO THE USE AND/OR SALE OF ST PRODUCTS INCLUDING WITHOUT LIMITATION IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION), OR INFRINGEMENT OF ANY PATENT, COPYRIGHT OR OTHER INTELLECTUAL PROPERTY RIGHT.

UNLESS EXPRESSLY APPROVED IN WRITING BY TWO AUTHORIZED ST REPRESENTATIVES, ST PRODUCTS ARE NOT RECOMMENDED, AUTHORIZED OR WARRANTED FOR USE IN MILITARY, AIR CRAFT, SPACE, LIFE SAVING, OR LIFE SUSTAINING APPLICATIONS, NOR IN PRODUCTS OR SYSTEMS WHERE FAILURE OR MALFUNCTION MAY RESULT IN PERSONAL INJURY, DEATH, OR SEVERE PROPERTY OR ENVIRONMENTAL DAMAGE. ST PRODUCTS WHICH ARE NOT SPECIFIED AS "AUTOMOTIVE GRADE" MAY ONLY BE USED IN AUTOMOTIVE APPLICATIONS AT USER'S OWN RISK.

Resale of ST products with provisions different from the statements and/or technical features set forth in this document shall immediately void any warranty granted by ST for the ST product or service described herein and shall not create or extend in any manner whatsoever, any liability of ST.

ST and the ST logo are trademarks or registered trademarks of ST in various countries.

Information in this document supersedes and replaces all information previously supplied.

The ST logo is a registered trademark of STMicroelectronics. All other names are the property of their respective owners.

© 2011 STMicroelectronics - All rights reserved

STMicroelectronics group of companies

Australia - Belgium - Brazil - Canada - China - Czech Republic - Finland - France - Germany - Hong Kong - India - Israel - Italy - Japan - Malaysia - Malta - Morocco - Philippines - Singapore - Spain - Sweden - Switzerland - United Kingdom - United States of America

www.st.com

